





**PRODUCT/PROCESS CHANGE NOTICE (PCN)**

**ATTACHMENT I - PCN # : F1712-01**

**PCN Type:** Material Change from RoHS 5 to Green  
**Data Sheet Change:** None  
 No change in moisture sensitivity level (MSL)

**Detail Of Change:**

This notification is to advise our customers that IDT is converting from RoHS5 to Green package materials to meet industry materials requirements.

The material set details of the current and replacement part is as shown in Table 1.

There is no change to the moisture performance.

Table 1: Assembly Material Sets for The Existing and Replacement Parts

	<b>Current Part (RoHS5)</b>	<b>Replacement Part (Green)</b>
Assembly Location	Amkor Taiwan ASE Taiwan	ASE Taiwan
Die bump	63Sn37Pb	Sn1.8Ag
Solder balls	Sn96.5/Ag3.0/Cu0.5	Sn96.5/Ag3.0/Cu0.5

**Affected Part List**

<b>Current Part# (RoHS5)</b>	<b>Replacement Part# (Green)</b>
80HCPS1616CHR	80HCPS1616CHLG
80HCPS1616CHRI	80HCPS1616CHLGI



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#### Qualification Information and Qualification Data:

**Affected Packages:** FCBGA-400

**Assembly Material:** Shown on page 2 of this attachment.

**Qual Plan & Results:** Tests are in accordance with JEDEC47 recommended tests.

**Qualification Vehicle:** FCBGA-784

Test Description	Test Method	Test Results (Rej / SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55°C to 125°C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - Unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	0/25	0/25	0/25
High Temperature Storage Bake (150°C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Solder Ball Shear Test	JESD22-B117	0/5	0/5	0/5
X Ray	IDT Spec. MAC-3012	0/45	0/45	0/45
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 4, 245 °C	0/25	0/25	0/25

\*Note: Tests were subjected to Preconditioning per JESD22-A113 prior to stress test